

Telect Modular E1 DSX Panels

Copper :: The Dynamic Solution for Copper Connectivity

Flexibility for today's networks... reliability for tomorrow

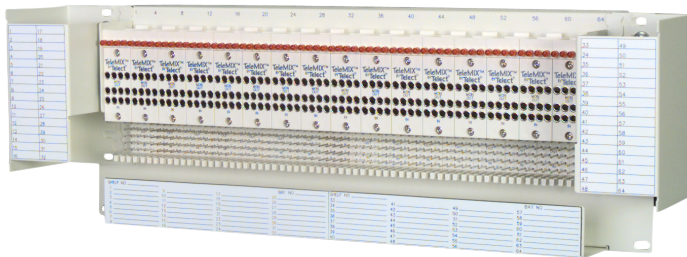
Modular Telect DSX panels provide a versatile, fully configurable platform for signal management in E1 network applications. The modular design enables customisation to fit the environment, as well as effective cost deferral and expense management – users can purchase and deploy connectivity modules as needed when circuits are ready to earn revenue.

With a variety of chassis and modules available, you can build a panel to fit specific network requirements. Each four-termination module snaps into place in the chassis. Choose from wire-wrap, coaxial or RJ48C connectors to fit your standards. The result is a high-quality, reliable and dynamic platform for cross-connecting, patching, testing and monitoring E1 circuits.

In use...a typical DSX application

With a modular DSX, you can add flexibility, versatility and advanced connectivity functionality to traditional E1 distribution frame applications. The DSX panel provides a multiple interface point for testing, patching, monitoring and cross-connecting E1 circuits. With three backplane options, you can terminate a variety of E1 switch and MUX equipment with a single set of components.

Individual modules snap into the chassis for instant power connection. The overall result is vastly improved cable management, distribution frame space savings and DSX capabilities (non-intrusive patch, test, monitor, cross-connect) for E1 systems.



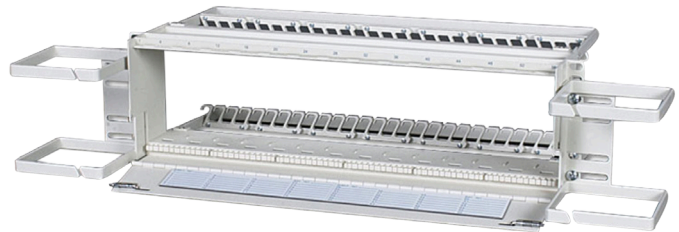
A fully loaded 64-termination modular DSX panel.

Telect DSX features and advantages

- Patch, monitor and cross-connect E1 circuits
- Choose fully configured high-density panels or empty chassis and individual four-port modules for flexibility
- Chassis and module options enable customisation
- Modules come with four jacks that accept all standard patch cords and accessories
- Wall-mount/total front access panels available for applications with limited rear access
- Modular design enables you to add modules as your application grows
- Telect DSX products include a lifetime guarantee

Options to fit the application

- Chassis: 483 mm (19-in.) and 584 mm (23-in.) sizes, 56 or 64 terminations
- Modules: 4-port DSX, with wire-wrap, coaxial or RJ48C I/O interface field



Choose from a variety of chassis (above) and modules (right) to build the panel that fits your application best. See reverse for ordering details



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Ordering Information

4000 Series System

| Description/Capacity | Dimensions | Part Number |
|---|--------------------------------|-----------------|
| 84-term./4 RU loaded panel | 584mmWx178mmHx211mm D | 010-4084-4011 |
| 64-term./3 RU loaded panel | 483mmWx133mmHx211mm D | 010-4064-4000 |
| 64-term./4 RU loaded panel | 483mmWx178mmHx211mm D | 010-4064-4010 |
| 64-term./4 RU loaded total front access panel | 483mmWx177mmHx135mm D | 010-4264-0001RE |
| 64-term./3 RU empty chassis (16 module capacity) | 483 mm W x 133 mm H x 211 mm D | 010-0000-4000 |
| 64-term./4 RU empty chassis (16 module capacity) | 483mmWx178mmHx211mm D | 010-0000-4010 |
| 56-term./3 RU empty chassis (14 module capacity) | 483 mm W x 133 mm H x 216 mm D | 010-0000-4006 |
| 56-term./4 RU empty chassis (14 module capacity) | 483mmWx178mmHx216mm D | 010-0000-4016 |
| 36-term. wall-mount empty chassis (9 module capacity) | 279 mm W x 178 mm H x 152 mm D | 010-0000-4020 |
| 8-term. wall-mount empty chassis (2 module capacity) | 53mmWx127mmHx79mmD | 010-0000-4030 |
| 4-termination E1 DSX module | | 010-4004-E100RE |
| 4-termination T1 DSX module | | 010-4004-0000 |

SuperMIX System

| | | |
|---|--------------------------------|-----------------|
| 56-term./3 RU chassis (14 module capacity) Includes 10 cm cable management rings | 483 mm W x 133 mm H x 240 mm D | 010-0000-2709 |
| 56-term./3 RU chassis (14 module capacity) | 483mmWx133mmHx240mm D | 010-0000-2702 |
| 64-term./3 RU chassis (16 module capacity) | 584 mm W x 133 mm H x 240 mm D | 010-0000-2701 |
| 4-term. module, wire-wrap I/O backplane | | 010-2704-1100RE |
| 4-term. module, BNC connector I/O backplane | | 010-2704-1200RE |
| 4-term. module, RJ48C connector I/O backplane | | 010-2704-1800RE |

Jack Specifications

| Connections | | Electrical | |
|---------------------|--|----------------|--|
| Jack type | E1 Standard Bantam | Insertion loss | BNC: 0.7 dB at 1.024 MHz Wire-wrap: 0.1 dB at 1.024 MHz |
| Environmental | | Crosstalk | BNC: Adjacent channel -70 dB at 1.024 MHz; inter-channel -70 dB at 1.024 MHz Wire-wrap: Adjacent channel -60 dB at 1.024 MHz; inter-channel -70 dB at 1.024 MHz |
| Salt spray | Per MIL-STD-202F, method 101D | Return loss | BNC: -20 dB at 1.024 MHz Wire-wrap: -30 dB at 1.024 MHz |
| Moisture resistance | Per MIL-STD-202F, method 106E | Monitor level | -20 dB (-1 dB + 0.5 dB) |
| Thermal limits | -40 to 65° C operating -55 to 85° C non-operating | | |
| Thermal shock | Per MIL-STD-202, method 107D | | |
| Humidity | 0 to 95% operating and non-operating | | |